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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	32
Number of Logic Elements/Cells	256
Total RAM Bits	-
Number of I/O	78
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	100-LFBGA, CSPBGA
Supplier Device Package	100-CSBGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo256e-4mn100i

Features

■ Non-volatile, Infinitely Reconfigurable

- Instant-on – powers up in microseconds
- Single chip, no external configuration memory required
- Excellent design security, no bit stream to intercept
- Reconfigure SRAM based logic in milliseconds
- SRAM and non-volatile memory programmable through JTAG port
- Supports background programming of non-volatile memory

■ Sleep Mode

- Allows up to 100x static current reduction

■ TransFR™ Reconfiguration (TFR)

- In-field logic update while system operates

■ High I/O to Logic Density

- 256 to 2280 LUT4s
- 73 to 271 I/Os with extensive package options
- Density migration supported
- Lead free/RoHS compliant packaging

■ Embedded and Distributed Memory

- Up to 27.6 Kbits sysMEM™ Embedded Block RAM
- Up to 7.7 Kbits distributed RAM
- Dedicated FIFO control logic

■ Flexible I/O Buffer

- Programmable sysIO™ buffer supports wide range of interfaces:
 - LVCMOS 3.3/2.5/1.8/1.5/1.2
 - LVTTTL
 - PCI
 - LVDS, Bus-LVDS, LVPECL, RSDS

■ sysCLOCK™ PLLs

- Up to two analog PLLs per device
- Clock multiply, divide, and phase shifting

■ System Level Support

- IEEE Standard 1149.1 Boundary Scan
- Onboard oscillator
- Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply
- IEEE 1532 compliant in-system programming

Introduction

The MachXO is optimized to meet the requirements of applications traditionally addressed by CPLDs and low capacity FPGAs: glue logic, bus bridging, bus interfacing, power-up control, and control logic. These devices bring together the best features of CPLD and FPGA devices on a single chip.

Table 1-1. MachXO Family Selection Guide

Device	LCMXO256	LCMXO640	LCMXO1200	LCMXO2280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V _{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
Packages				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

Modes of Operation

Each Slice is capable of four modes of operation: Logic, Ripple, RAM, and ROM. The Slice in the PFF is capable of all modes except RAM. Table 2-2 lists the modes and the capability of the Slice blocks.

Table 2-2. Slice Modes

	Logic	Ripple	RAM	ROM
PFU Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	SP 16x2	ROM 16x1 x 2
PFF Slice	LUT 4x2 or LUT 5x1	2-bit Arithmetic Unit	N/A	ROM 16x1 x 2

Logic Mode: In this mode, the LUTs in each Slice are configured as 4-input combinatorial lookup tables (LUT4). A LUT4 can have 16 possible input combinations. Any logic function with four inputs can be generated by programming this lookup table. Since there are two LUT4s per Slice, a LUT5 can be constructed within one Slice. Larger lookup tables such as LUT6, LUT7, and LUT8 can be constructed by concatenating other Slices.

Ripple Mode: Ripple mode allows the efficient implementation of small arithmetic functions. In ripple mode, the following functions can be implemented by each Slice:

- Addition 2-bit
- Subtraction 2-bit
- Add/Subtract 2-bit using dynamic control
- Up counter 2-bit
- Down counter 2-bit
- Ripple mode multiplier building block
- Comparator functions of A and B inputs
 - A greater-than-or-equal-to B
 - A not-equal-to B
 - A less-than-or-equal-to B

Two additional signals, Carry Generate and Carry Propagate, are generated per Slice in this mode, allowing fast arithmetic functions to be constructed by concatenating Slices.

RAM Mode: In this mode, distributed RAM can be constructed using each LUT block as a 16x2-bit memory. Through the combination of LUTs and Slices, a variety of different memories can be constructed.

The ispLEVER design tool supports the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-6 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices. One Slice functions as the read-write port, while the other companion Slice supports the read-only port. For more information on RAM mode in MachXO devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required For Implementing Distributed RAM

	SPR16x2	DPR16x2
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

The EBR memory supports three forms of write behavior for single or dual port operation:

1. **Normal** – data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** – a copy of the input data appears at the output of the same port. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2^N-1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.

of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC} , V_{CCAUX} , and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. Left and Right sysIO Buffer Pairs

The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to V_{CCIO} . The I/O pins will maintain the blank configuration until V_{CC} , V_{CCAUX} and V_{CCIO} have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Table 2-10. Supported Output Standards

Output Standard	Drive	V _{CCIO} (Typ.)
Single-ended Interfaces		
LVTTTL	4mA, 8mA, 12mA, 16mA	3.3
LVC MOS33	4mA, 8mA, 12mA, 14mA	3.3
LVC MOS25	4mA, 8mA, 12mA, 14mA	2.5
LVC MOS18	4mA, 8mA, 12mA, 14mA	1.8
LVC MOS15	4mA, 8mA	1.5
LVC MOS12	2mA, 6mA	1.2
LVC MOS33, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS25, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS18, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS15, Open Drain	4mA, 8mA	—
LVC MOS12, Open Drain	2mA, 6mA	—
PCI33 ³	N/A	3.3
Differential Interfaces		
LVDS ^{1, 2}	N/A	2.5
BLVDS, RSDS ²	N/A	2.5
LVPECL ²	N/A	3.3

1. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers.

2. These interfaces can be emulated with external resistors in all devices.

3. Top Banks of MachXO1200 and MachXO2280 devices only.

sysIO Buffer Banks

The number of Banks vary between the devices of this family. Eight Banks surround the two larger devices, the MachXO1200 and MachXO2280 (two Banks per side). The MachXO640 has four Banks (one Bank per side). The smallest member of this family, the MachXO256, has only two Banks.

Each sysIO buffer Bank is capable of supporting multiple I/O standards. Each Bank has its own I/O supply voltage (V_{CCIO}) which allows it to be completely independent from the other Banks. Figure 2-18, Figure 2-18, Figure 2-20 and Figure 2-21 shows the sysIO Banks and their associated supplies for all devices.

Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

Leave Alone I/O

When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#) for details.

Security

The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

sysIO Recommended Operating Conditions

Standard	V _{CCIO} (V)		
	Min.	Typ.	Max.
LVC MOS 3.3	3.135	3.3	3.465
LVC MOS 2.5	2.375	2.5	2.625
LVC MOS 1.8	1.71	1.8	1.89
LVC MOS 1.5	1.425	1.5	1.575
LVC MOS 1.2	1.14	1.2	1.26
LVTTL	3.135	3.3	3.465
PCI ³	3.135	3.3	3.465
LVDS ^{1,2}	2.375	2.5	2.625
LVPECL ¹	3.135	3.3	3.465
BLVDS ¹	2.375	2.5	2.625
RSDS ¹	2.375	2.5	2.625

1. Inputs on chip. Outputs are implemented with the addition of external resistors.
2. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers
3. Input on the top bank of the MachXO1200 and MachXO2280 only.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V _{IL}		V _{IH}		V _{OL} Max. (V)	V _{OH} Min. (V)	I _{OL} ¹ (mA)	I _{OH} ¹ (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVC MOS 3.3	-0.3	0.8	2.0	3.6	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	2.4	16	-16
					0.4	V _{CCIO} - 0.4	12, 8, 4	-12, -8, -4
LVC MOS 2.5	-0.3	0.7	1.7	3.6	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.8	-0.3	0.35V _{CCIO}	0.65V _{CCIO}	3.6	0.4	V _{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.5	-0.3	0.35V _{CCIO}	0.65V _{CCIO}	3.6	0.4	V _{CCIO} - 0.4	8, 4	-8, -4
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.2 ("C" Version)	-0.3	0.42	0.78	3.6	0.4	V _{CCIO} - 0.4	6, 2	-6, -2
					0.2	V _{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.2 ("E" Version)	-0.3	0.35V _{CC}	0.65V _{CC}	3.6	0.4	V _{CCIO} - 0.4	6, 2	-6, -2
					0.2	V _{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	0.3V _{CCIO}	0.5V _{CCIO}	3.6	0.1V _{CCIO}	0.9V _{CCIO}	1.5	-0.5

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O Bank and the end of an I/O Bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between Bank GND connections or between the last GND in a Bank and the end of a Bank.

Typical Building Block Function Performance¹

Pin-to-Pin Performance (LVCMOS25 12mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

Register-to-Register Performance

Function	-5 Timing	Units
Basic Functions		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
Embedded Memory Functions (1200 and 2280 Devices Only)		
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
Distributed Memory Functions		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

1. The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

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Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

Switching Test Conditions

Figure 3-6 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-6. Output Test Load, LVTTTL and LVCMOS Standards

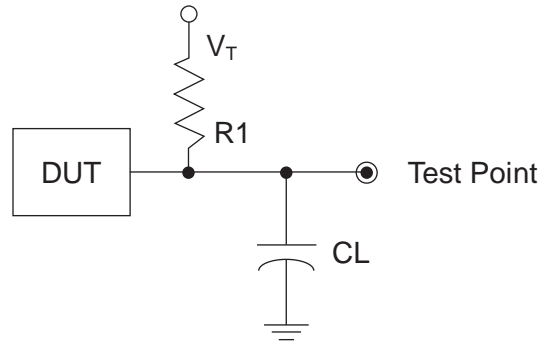


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTTL and LVCMOS settings (L -> H, H -> L)	∞	0pF	LVTTTL, LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVTTTL and LVCMOS 3.3 (Z -> H)	188	0pF	1.5	V_{OL}
LVTTTL and LVCMOS 3.3 (Z -> L)				V_{OH}
Other LVCMOS (Z -> H)			$V_{CCIO}/2$	V_{OL}
Other LVCMOS (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVTTTL + LVCMOS (H -> Z)			$V_{OH} - 0.15$	V_{OL}
LVTTTL + LVCMOS (L -> Z)			$V_{OL} - 0.15$	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

LCMX0256 and LCMX0640 Logic Signal Connections: 100 TQFP

Pin Number	LCMX0256				LCMX0640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	1		T	PL2A	3		T
2	PL2B	1		C	PL2C	3		T
3	PL3A	1		T	PL2B	3		C
4	PL3B	1		C	PL2D	3		C
5	PL3C	1		T	PL3A	3		T
6	PL3D	1		C	PL3B	3		C
7	PL4A	1		T	PL3C	3		T
8	PL4B	1		C	PL3D	3		C
9	PL5A	1		T	PL4A	3		
10	VCCIO1	1			VCCIO3	3		
11	PL5B	1		C	PL4C	3		T
12	GNDIO1	1			GNDIO3	3		
13	PL5C	1		T	PL4D	3		C
14	PL5D	1	GSRN	C	PL5B	3	GSRN	
15	PL6A	1		T	PL7B	3		
16	PL6B	1	TSALL	C	PL8C	3	TSALL	T
17	PL7A	1		T	PL8D	3		C
18	PL7B	1		C	PL9A	3		
19	PL7C	1		T	PL9C	3		
20	PL7D	1		C	PL10A	3		
21	PL8A	1		T	PL10C	3		
22	PL8B	1		C	PL11A	3		
23	PL9A	1		T	PL11C	3		
24	VCCIO1	1			VCCIO3	3		
25	GNDIO1	1			GNDIO3	3		
26	TMS	1	TMS		TMS	2	TMS	
27	PL9B	1		C	PB2C	2		
28	TCK	1	TCK		TCK	2	TCK	
29	PB2A	1		T	VCCIO2	2		
30	PB2B	1		C	GNDIO2	2		
31	TDO	1	TDO		TDO	2	TDO	
32	PB2C	1		T	PB4C	2		
33	TDI	1	TDI		TDI	2	TDI	
34	PB2D	1		C	PB4E	2		
35	VCC	-			VCC	-		
36	PB3A	1	PCLK1_1**	T	PB5B	2	PCLK2_1**	
37	PB3B	1		C	PB5D	2		
38	PB3C	1	PCLK1_0**	T	PB6B	2	PCLK2_0**	
39	PB3D	1		C	PB6C	2		
40	GND	-			GND	-		
41	VCCIO1	1			VCCIO2	2		
42	GNDIO1	1			GNDIO2	2		

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	3		T	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2C	3		T	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL2B	3		C	PL3A	7		T*	PL3A	7		T*
4	PL3A	3		T	PL3B	7		C*	PL3B	7		C*
5	PL2D	3		C	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
6	PL3B	3		C	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
7	PL3C	3		T	PL4A	7		T*	PL4A	7		T*
8	PL3D	3		C	PL4B	7		C*	PL4B	7		C*
9	PL4A	3			PL4C	7			PL4C	7		
10	VCCIO3	3			VCCIO7	7			VCCIO7	7		
11	GNDIO3	3			GNDIO7	7			GNDIO7	7		
12	PL4D	3			PL5C	7			PL6C	7		
13	PL5A	3		T	PL6A	7		T*	PL7A	7		T*
14	PL5B	3	GSRN	C	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
15	PL5D	3			PL6D	7			PL7D	7		
16	GND	-			GND	-			GND	-		
17	PL6C	3		T	PL7C	7		T	PL9C	7		T
18	PL6D	3		C	PL7D	7		C	PL9D	7		C
19	PL7A	3		T	PL10A	6		T*	PL13A	6		T*
20	PL7B	3		C	PL10B	6		C*	PL13B	6		C*
21	VCC	-			VCC	-			VCC	-		
22	PL8A	3		T	PL11A	6		T*	PL13D	6		
23	PL8B	3		C	PL11B	6		C*	PL14D	6		C
24	PL8C	3	TSALL		PL11C	6	TSALL		PL14C	6	TSALL	T
25	PL9C	3		T	PL12B	6			PL15B	6		
26	VCCIO3	3			VCCIO6	6			VCCIO6	6		
27	GNDIO3	3			GNDIO6	6			GNDIO6	6		
28	PL9D	3		C	PL13D	6			PL16D	6		
29	PL10A	3		T	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
30	PL10B	3		C	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
31	PL10C	3		T	PL14C	6		T	PL17C	6		T
32	PL11A	3		T	PL14D	6		C	PL17D	6		C
33	PL10D	3		C	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
34	PL11C	3		T	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
35	PL11B	3		C	PL16A	6		T	PL19A	6		T
36	PL11D	3		C	PL16B	6		C	PL19B	6		C
37	GNDIO2	2			GNDIO5	5			GNDIO5	5		
38	VCCIO2	2			VCCIO5	5			VCCIO5	5		
39	TMS	2	TMS		TMS	5	TMS		TMS	5	TMS	
40	PB2C	2			PB2C	5		T	PB2A	5		T
41	PB3A	2		T	PB2D	5		C	PB2B	5		C
42	TCK	2	TCK		TCK	5	TCK		TCK	5	TCK	
43	PB3B	2		C	PB3A	5		T	PB3A	5		T
44	PB3C	2		T	PB3B	5		C	PB3B	5		C
45	PB3D	2		C	PB4A	5		T	PB4A	5		T
46	PB4A	2		T	PB4B	5		C	PB4B	5		C
47	TDO	2	TDO		TDO	5	TDO		TDO	5	TDO	
48	PB4B	2		C	PB4D	5			PB4D	5		
49	PB4C	2		T	PB5A	5		T	PB5A	5		T
50	PB4D	2		C	PB5B	5		C	PB5B	5		C

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
D3	NC				D3	PT2C	0		T	D3	PT3C	0		T
A3	PT2B	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2A	0		T	A2	PT3A	0		T	A2	PT3A	0		T
B3	NC				B3	PT2B	0		C	B3	PT2D	0		C
B2	NC				B2	PT2A	0		T	B2	PT2C	0		T
VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0		
GND	GNDIO0	0			GND	GNDIO0	0			GND	GNDIO0	0		
A1	GND	-			A1	GND	-			A1	GND	-		
A16	GND	-			A16	GND	-			A16	GND	-		
F11	GND	-			F11	GND	-			F11	GND	-		
G8	GND	-			G8	GND	-			G8	GND	-		
G9	GND	-			G9	GND	-			G9	GND	-		
H7	GND	-			H7	GND	-			H7	GND	-		
H8	GND	-			H8	GND	-			H8	GND	-		
H9	GND	-			H9	GND	-			H9	GND	-		
H10	GND	-			H10	GND	-			H10	GND	-		
J7	GND	-			J7	GND	-			J7	GND	-		
J8	GND	-			J8	GND	-			J8	GND	-		
J9	GND	-			J9	GND	-			J9	GND	-		
J10	GND	-			J10	GND	-			J10	GND	-		
K8	GND	-			K8	GND	-			K8	GND	-		
K9	GND	-			K9	GND	-			K9	GND	-		
L6	GND	-			L6	GND	-			L6	GND	-		
T1	GND	-			T1	GND	-			T1	GND	-		
T16	GND	-			T16	GND	-			T16	GND	-		
G7	VCC	-			G7	VCC	-			G7	VCC	-		
G10	VCC	-			G10	VCC	-			G10	VCC	-		
K7	VCC	-			K7	VCC	-			K7	VCC	-		
K10	VCC	-			K10	VCC	-			K10	VCC	-		
H6	VCCIO3	3			H6	VCCIO7	7			H6	VCCIO7	7		
G6	VCCIO3	3			G6	VCCIO7	7			G6	VCCIO7	7		
K6	VCCIO3	3			K6	VCCIO6	6			K6	VCCIO6	6		
J6	VCCIO3	3			J6	VCCIO6	6			J6	VCCIO6	6		
L8	VCCIO2	2			L8	VCCIO5	5			L8	VCCIO5	5		
L7	VCCIO2	2			L7	VCCIO5	5			L7	VCCIO5	5		
L9	VCCIO2	2			L9	VCCIO4	4			L9	VCCIO4	4		
L10	VCCIO2	2			L10	VCCIO4	4			L10	VCCIO4	4		
K11	VCCIO1	1			K11	VCCIO3	3			K11	VCCIO3	3		
J11	VCCIO1	1			J11	VCCIO3	3			J11	VCCIO3	3		
H11	VCCIO1	1			H11	VCCIO2	2			H11	VCCIO2	2		
G11	VCCIO1	1			G11	VCCIO2	2			G11	VCCIO2	2		
F9	VCCIO0	0			F9	VCCIO1	1			F9	VCCIO1	1		
F10	VCCIO0	0			F10	VCCIO1	1			F10	VCCIO1	1		
F8	VCCIO0	0			F8	VCCIO0	0			F8	VCCIO0	0		
F7	VCCIO0	0			F7	VCCIO0	0			F7	VCCIO0	0		

* Supports true LVDS outputs.

** NC for "E" devices.

*** Primary clock inputs are single-ended.

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
V10	PB9B	4		C
N10	PB9C	4		T
R10	PB9D	4		C
P10	PB10F	4	PCLK4_1***	C
T10	PB10E	4		T
U10	PB10D	4		C
V11	PB10C	4		T
U11	PB10B	4	PCLK4_0***	C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
T11	PB10A	4		T
U12	PB11A	4		T
R11	PB11B	4		C
GND	GND	-		
T12	PB11C	4		T
P11	PB11D	4		C
V12	PB12A	4		T
V13	PB12B	4		C
R12	PB12C	4		T
N11	PB12D	4		C
U13	PB12E	4		T
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
V14	PB12F	4		C
T13	PB13A	4		T
P12	PB13B	4		C
R13	PB13C	4		T
N12	PB13D	4		C
V15	PB14A	4		T
U14	PB14B	4		C
V16	PB14C	4		T
GND	GND	-		
T14	PB14D	4		C
U15	PB15A	4		T
V17	PB15B	4		C
P13**	SLEEPN	-	SLEEPN	
T15	PB15D	4		
U16	PB16A	4		T
V18	PB16B	4		C
N13	PB16C	4		T
R14	PB16D	4		C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
F16	GND	-		
H10	GND	-		
H11	GND	-		
H8	GND	-		
H9	GND	-		
J10	GND	-		
J11	GND	-		
J4	GND	-		
J8	GND	-		
J9	GND	-		
K10	GND	-		
K11	GND	-		
K17	GND	-		
K8	GND	-		
K9	GND	-		
L10	GND	-		
L11	GND	-		
L8	GND	-		
L9	GND	-		
N2	GND	-		
P14	GND	-		
P5	GND	-		
R7	GND	-		
F14	VCC	-		
G11	VCC	-		
G9	VCC	-		
H7	VCC	-		
L7	VCC	-		
M9	VCC	-		
H6	VCCIO7	7		
J7	VCCIO7	7		
M7	VCCIO6	6		
K7	VCCIO6	6		
M8	VCCIO5	5		
R9	VCCIO5	5		
M12	VCCIO4	4		
M11	VCCIO4	4		
L12	VCCIO3	3		
K12	VCCIO3	3		
J12	VCCIO2	2		
H12	VCCIO2	2		
G12	VCCIO1	1		
G10	VCCIO1	1		

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

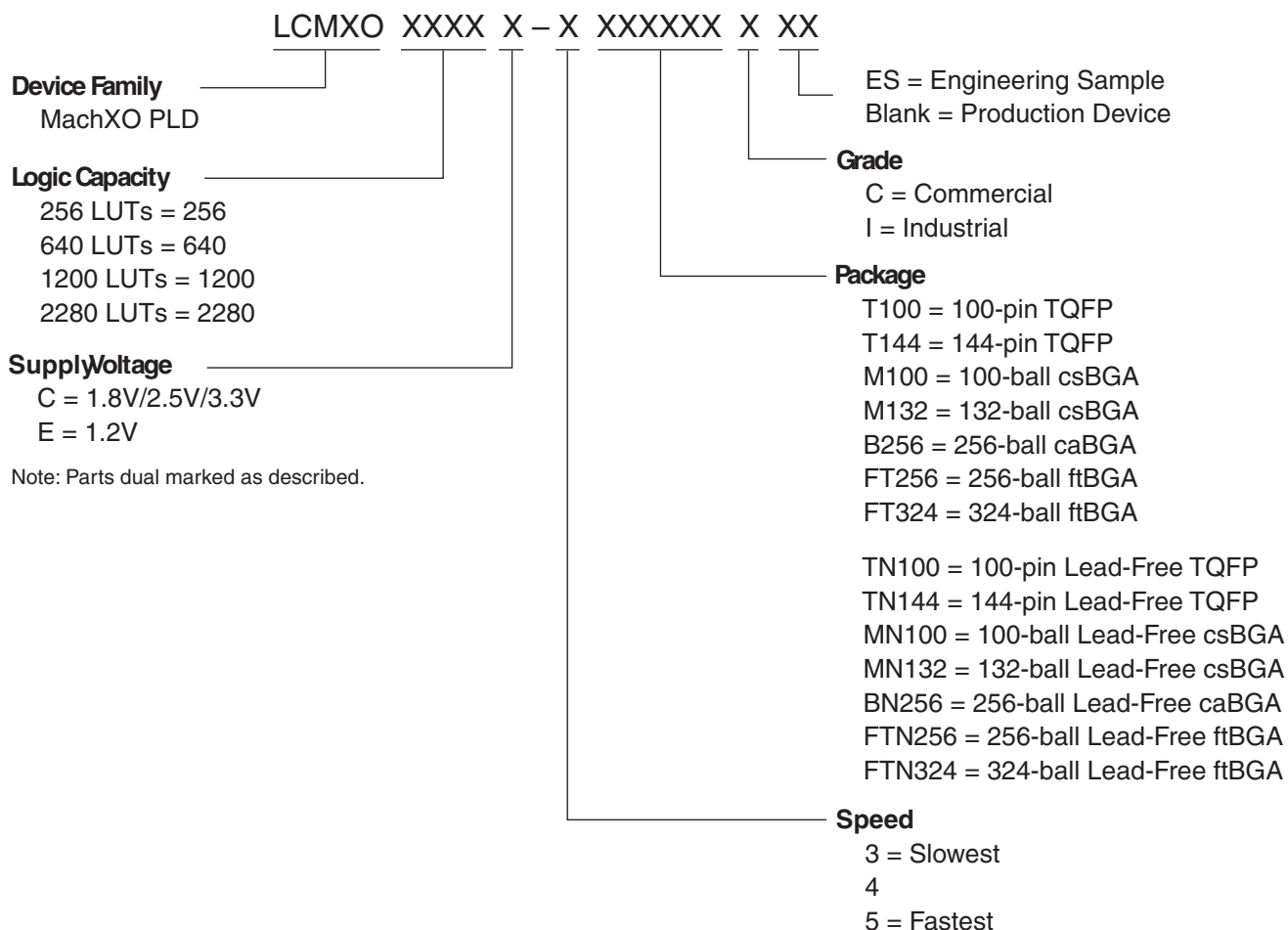
LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
G8	VCCIO0	0		
G7	VCCIO0	0		

* Supports true LVDS outputs.

** NC for "E" devices.

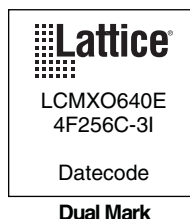
*** Primary clock inputs are single-ended.

Part Number Description



Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device. For example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade. The slowest commercial speed grade does not have industrial markings. The markings appears as follows:



Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3T100I	256	1.2V	78	-3	TQFP	100	IND
LCMXO256E-4T100I	256	1.2V	78	-4	TQFP	100	IND
LCMXO256E-3M100I	256	1.2V	78	-3	csBGA	100	IND
LCMXO256E-4M100I	256	1.2V	78	-4	csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3T100I	640	1.2V	74	-3	TQFP	100	IND
LCMXO640E-4T100I	640	1.2V	74	-4	TQFP	100	IND
LCMXO640E-3M100I	640	1.2V	74	-3	csBGA	100	IND
LCMXO640E-4M100I	640	1.2V	74	-4	csBGA	100	IND
LCMXO640E-3T144I	640	1.2V	113	-3	TQFP	144	IND
LCMXO640E-4T144I	640	1.2V	113	-4	TQFP	144	IND
LCMXO640E-3M132I	640	1.2V	101	-3	csBGA	132	IND
LCMXO640E-4M132I	640	1.2V	101	-4	csBGA	132	IND
LCMXO640E-3B256I	640	1.2V	159	-3	caBGA	256	IND
LCMXO640E-4B256I	640	1.2V	159	-4	caBGA	256	IND
LCMXO640E-3FT256I	640	1.2V	159	-3	ftBGA	256	IND
LCMXO640E-4FT256I	640	1.2V	159	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3T100I	1200	1.2V	73	-3	TQFP	100	IND
LCMXO1200E-4T100I	1200	1.2V	73	-4	TQFP	100	IND
LCMXO1200E-3T144I	1200	1.2V	113	-3	TQFP	144	IND
LCMXO1200E-4T144I	1200	1.2V	113	-4	TQFP	144	IND
LCMXO1200E-3M132I	1200	1.2V	101	-3	csBGA	132	IND
LCMXO1200E-4M132I	1200	1.2V	101	-4	csBGA	132	IND
LCMXO1200E-3B256I	1200	1.2V	211	-3	caBGA	256	IND
LCMXO1200E-4B256I	1200	1.2V	211	-4	caBGA	256	IND
LCMXO1200E-3FT256I	1200	1.2V	211	-3	ftBGA	256	IND
LCMXO1200E-4FT256I	1200	1.2V	211	-4	ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3T100I	2280	1.2V	73	-3	TQFP	100	IND
LCMXO2280E-4T100I	2280	1.2V	73	-4	TQFP	100	IND
LCMXO2280E-3T144I	2280	1.2V	113	-3	TQFP	144	IND
LCMXO2280E-4T144I	2280	1.2V	113	-4	TQFP	144	IND
LCMXO2280E-3M132I	2280	1.2V	101	-3	csBGA	132	IND
LCMXO2280E-4M132I	2280	1.2V	101	-4	csBGA	132	IND
LCMXO2280E-3B256I	2280	1.2V	211	-3	caBGA	256	IND
LCMXO2280E-4B256I	2280	1.2V	211	-4	caBGA	256	IND
LCMXO2280E-3FT256I	2280	1.2V	211	-3	ftBGA	256	IND
LCMXO2280E-4FT256I	2280	1.2V	211	-4	ftBGA	256	IND
LCMXO2280E-3FT324I	2280	1.2V	271	-3	ftBGA	324	IND
LCMXO2280E-4FT324I	2280	1.2V	271	-4	ftBGA	324	IND

Lead-Free Packaging
Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3TN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	COM
LCMXO256C-4TN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	COM
LCMXO256C-5TN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free TQFP	100	COM
LCMXO256C-3MN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	COM
LCMXO256C-4MN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	COM
LCMXO256C-5MN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3TN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	COM
LCMXO640C-4TN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	COM
LCMXO640C-5TN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free TQFP	100	COM
LCMXO640C-3MN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	COM
LCMXO640C-4MN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	COM
LCMXO640C-5MN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free csBGA	100	COM
LCMXO640C-3TN144C	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO640C-4TN144C	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO640C-5TN144C	640	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO640C-3MN132C	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO640C-4MN132C	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO640C-5MN132C	640	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO640C-3BN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	COM
LCMXO640C-4BN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	COM
LCMXO640C-5BN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free caBGA	256	COM
LCMXO640C-3FTN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	COM
LCMXO640C-4FTN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	COM
LCMXO640C-5FTN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3TN100C	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	COM
LCMXO1200C-4TN100C	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	COM
LCMXO1200C-5TN100C	1200	1.8V/2.5V/3.3V	73	-5	Lead-Free TQFP	100	COM
LCMXO1200C-3TN144C	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO1200C-4TN144C	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO1200C-5TN144C	1200	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO1200C-3MN132C	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO1200C-4MN132C	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO1200C-5MN132C	1200	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO1200C-3BN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	COM
LCMXO1200C-4BN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	COM
LCMXO1200C-5BN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free caBGA	256	COM
LCMXO1200C-3FTN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	COM
LCMXO1200C-4FTN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	COM
LCMXO1200C-5FTN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free ftBGA	256	COM

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
			Security section updated.
		DC and Switching Characteristics	Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timing updated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
			JTAG Port Timing Specification updated (rev. A 0.16).
		Pinout Information	SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connection section has been updated to include all devices/packages.
		Ordering Information	Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.